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(54) Title: POLISHING PAD HAVING EDGE SURFACE TREATMENT

(57) **Abstract:** The present invention is directed to a polishing pad having a sublayer and a polishing layer. The surface of the outer peripheral edge of the sublayer can be at least partially treated to reduce the absorption or permeation of polishing fluid into the sublayer through the outer peripheral edge. The application of the surface treatment at least reduces the amount of polishing fluid absorbed by the sublayer of the polishing pad during the polishing process. The polishing pad of the present invention is useful in polishing microelectronic substrates and especially useful in chemical mechanical planarization of semiconductor wafers.



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